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COMPACT MODULE DELIVERS 39 TOPS AI PERFORMANCE

New COM Express Compact modules with AMD Ryzen Embedded 8000 Series for high-performance AI applications at the edge

Based on the dedicated computing cores of the new Ryzen processors featuring up to eight 'Zen 4' cores, innovative XDNA™ NPU, and powerful Radeon RDNA 3™ graphics, the new modules deliver impressive performance of up to 39 tera operations per second (TOPS) for AI inference.

This makes the new conga-TCR8 Type 6 modules particularly appealing for high-volume, price-sensitive applications requiring a combination of advanced AI, graphics, and computing power. OEMs in medical imaging, test & measurement, AI-supported POS/POI systems, and professional gaming can leverage these long-term available COM Express Compact modules to accelerate innovation while ensuring investment security. With a broad, scalable TDP range of 15 to 54 Watt, these modules are also ideal for upgrading existing designs. By simply replacing modules, companies can bring their products to the latest state of the art, significantly improving lifecycle, ROI, and sustainability.

- Up to 8 Zen 4 cores
- AMD Radeon RDNA 3 graphics
- AMD XDNA NPU
- Up to 128 GB RAM (optional with ECC)
- TDP range from 15W to 54W
- Onboard NVMe SSD (option)

For full product
info and datasheet
Click here

Congatec

Congatec is a rapidly growing technology company focussing on high-performance embedded computing products, so-called computer-on-modules and industrial single board computer.